





Applicable standard					
Rating	Operating temperature range	-35°C to +85°C(Notes 1)	Storage temperature range	-10°C to +60°C(Note3)	
	Operating humidity range	20 % to 80 % (Notes 2)	Storage humidity range	40 % to 70 %(Note3)	
	Voltage	150 V AC (DC)	Current	1 A/pin	
	Applicable Connector	DF13-*DS-1.25C	Applicable Contact	DF13(G)-2630SCF DF13-3032SCF	
Specifications					
Item		Test method	Requirements	QT	AT
Construction					
General examination		Visually and by measuring instrument.	According to drawing.	X	X
Marking		Confirmed visually.		X	X
Electric characteristics					
Contact resistance		AC 20mV, 1mA (DC OR 1000 Hz).	30 mΩ MAX.	X	—
Insulation resistance		100 V DC.	500 MΩ MIN.	X	—
Voltage proof		500 V AC for 1 min.	No flashover or breakdown.	X	—
Mechanical characteristics					
Mechanical operation		30 times insertions and extractions.	1) Contact resistance: 30 mΩ MAX. 2) No damage, crack or looseness of parts.	X	—
Vibration		Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 2 h, for 3 directions.	1) No electrical discontinuity of 1μs. 2) No damage, crack or looseness of parts.	X	—
Shock		490 m/s ² duration of pulse 11 ms at 3 times for 3 directions.		X	—
Environmental characteristics					
Rapid change of temperature 		Temperature -55°C→ +85°C Time 30min→ 30min Under 5 Cycles. (The transferring time of the tank is 2 to 3 MIN)	1) Contact resistance: 30mΩ MAX. 2) Insulation resistance: 500 MΩ MIN. 3) No damage, crack or looseness of parts.	X	—
Damp heat (Steady state)		Exposed at 40±2 °C, 90 to 95 %, 96 h.		X	—
Resistance to soldering heat		1) Reflow soldering « Reflow area » 250°C MAX 10 sec MAX 230°C MIN 60 sec MAX « Preheating area » 170°C to 190°C 60 sec to 120 sec Put through in reflow furnace twice, leave in ambient temperature and humidity for 1 hour. 2) Manual soldering Soldering iron temperature :300°C, Soldering time: 3sec. No strength on contact.	No deformation of case of excessive looseness of the terminals.	X	—
Solderability		Soldered at solder temperature, 245°C for insertion duration, 3sec.	Solder shall cover a minimum of 95 % of the surface being immersed.	X	—
Remarks					
Note 1: Include the temperature rising by current.					
Note 2: No condensing					
Note 3: Apply to the condition of long term storage for unused products before mounted on PCB. After mounted on PCB, operating temperature and humidity range is applied for interim storage during transportation.					
	Count	Description of revisions	Designed	Checked	Date
	1	DIS-H-00009653	HT. SATO	SZ. ONO	20210608
Unless otherwise specified , refer to IEC 60512.			Approved	HS. OKAWA	20200313
			Checked	TS. KUMAZAWA	20200313
			Designed	HK. HAYASHI	20200313
			Drawn	DS. HIROWATARI	20200306
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			Drawing no.	ELC-367982-22-00	
	Specification sheet		Part no.	DF13EA-*DP-1. 25V (22)	
	Hirose electric co., ltd.		Code no.	CL536	 1/1